Product End-of-Life Disassembly Instructions

Product Category: Notebooks
Marketing Name / Model [List multiple models if applicable.]
HP Elite x360 1040 14 inch G11 2-in-1
HP Elite x360 1040 14 inch G11 2-in-1 Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☒ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☒ Power supply PCB ☐ External Keyboard (KB) ☐ External Mouse ☒ Others: (1) Wireless module8 (2) Touch Panel control board PCA (3) NFC (4) Transfer board (5) HUB board (6) PMIC board (7) TP module	11
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☐ RTC/CMOS battery ☐ Others: _____	0
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☒ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	1

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☒ Panel LCD	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☐ Power Supply capacitor(s) or condenser(s)	0
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	Philip #0 #1
Screwdriver	Torx T8
Heatgun	N/A
Suction cup	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Follow steps described in disassembly instruction & operation name in 3.2 section.
2. If parts can be removed without using a tool, remove it first.
3. Use correct screwdriver and torque value before unlocking the screw.

3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

MANUFACTURING PROCESS INSTRUCTIONS
MECHANICAL ASSEMBLY

Sub-assemblyname:			
Written by:	zhao.neil	Revision:	1.00
Date:	2024/3/1	Page:	1 of 38

A.Current station version list:

Station	Version	Station	Version	Station	Version	Station	Version	Station	Version	Station	Version
1	1.00	11	1.00	21	1.00	31	1.00				
2	1.00	12	1.00	22	1.00	32	1.00				
3	1.00	13	1.00	23	1.00	33	1.00				
4	1.00	14	1.00	24	1.00	34	1.00				
5	1.00	15	1.00	25	1.00	35	1.00				
6	1.00	16	1.00	26	1.00	36	1.00				
7	1.00	17	1.00	27	1.00	37	1.00				
8	1.00	18	1.00	28	1.00						
9	1.00	19	1.00	29	1.00						
10	1.00	20	1.00	30	1.00						

B.Version Modify list:

Date	Sta.	Content	Ver.	Design
2024/3/1	ALL	First production	1.**	zhao.neil

审核： Zhao.neil 编制 ： Zhao.neil

编号:3QBMDAP001-F002 版本 :3 机密等级:一般 使用形式:纸质档 保存期限:最新版本 销毁方式:撕毁

HP Inc. instructions for this template are available at EL-MF877-01

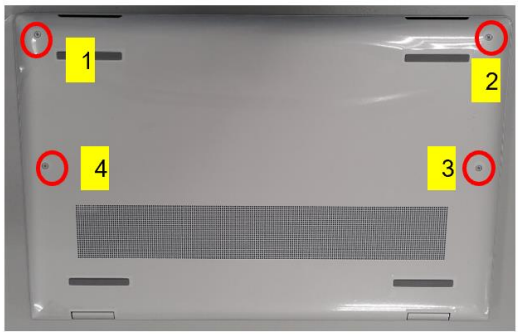
Standard operation guideline

Station: 1(1/1)

Operation name : disassemble D door Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble the door Set screw *4 (PIC —)
   - ❖ Torsion : 2.5 ± 0.2 kgf · cm
2. Toward down remove the Door(PIC —)





PIC —

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

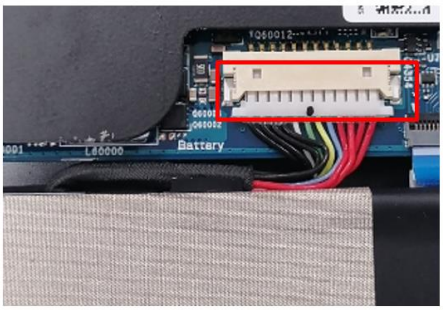
NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

Station: 2(1/1)

Operation name : disassemble cable Ver. : 1.00 Date : 2024/3/1

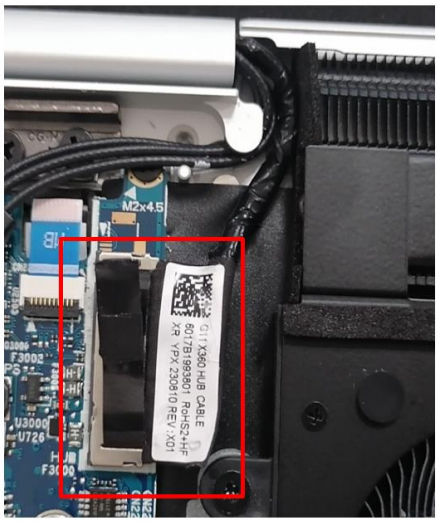


Pic 一

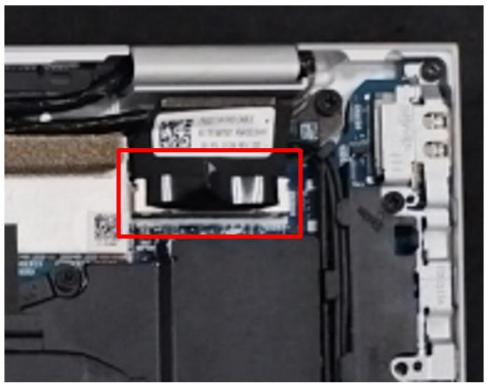
Step :

1. Disassemble battery Cable（PIC 一）
2. Disassemble camera Cable (PIC 二)
3. Disassemble EDP Cable (PIC三)

❖ Toward up black drawstring



PIC 二



PIC 三

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 3(1/1)

Operation name : disassemble Battery Ver. : 1.00 Date : 2024/3/1

Step :

1. Rotate Battery Frame · take out battery(PIC—)



Left – handed Battery Frame

right – handed Battery Frame

PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

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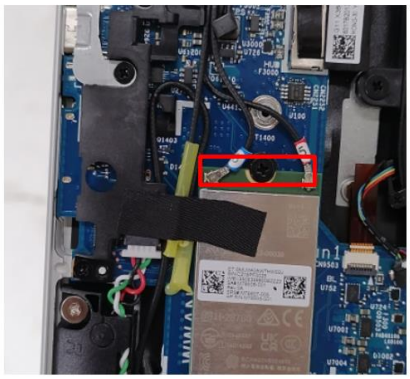
Standard operation guideline

Station: 4 (1/1)

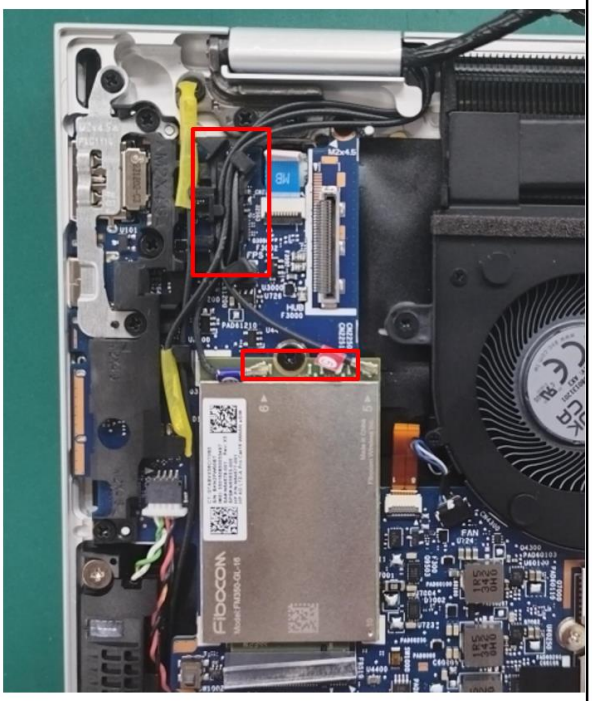
Operation name : disassemble WWAN Antenna Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble WWAN Antenna from WWAN Card CONN 、Frame hook (PIC —)







Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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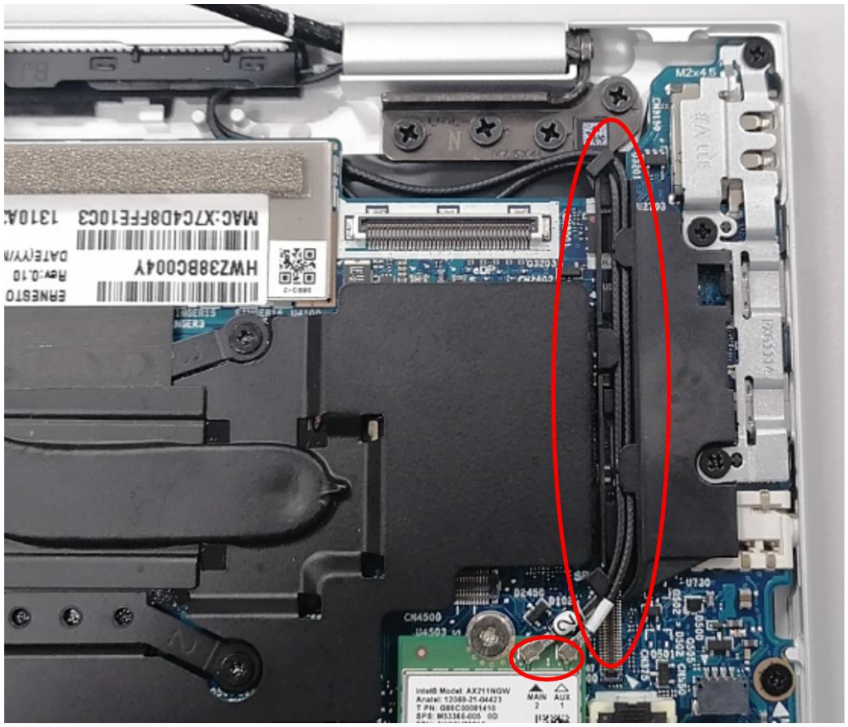
Standard operation guideline

Station: 5(1/1)

Operation name : disassemble WWAN Antenna Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble WLAN Antenna from WLAN card connector、Frame hook (PIC —)



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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Standard operation guideline

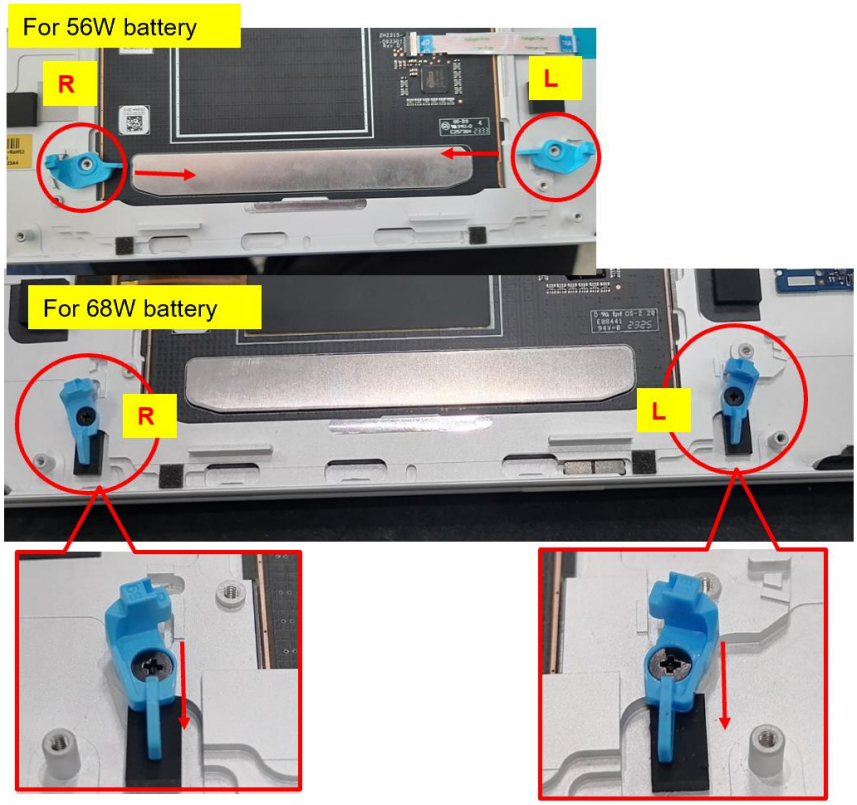
Station: 6(1/1)

Operation name : disassemble battery Frame Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble screw M2*3(6052B0120001)，remove latch

◆ Torsion：2 ± 0.2 kgf · cm



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 7(1/1)

Operation name : Disassemble Speaker Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble speaker screw M2x2L(6052B0156201)*6，take out speaker CNTR，remove speaker
   - ◆ Torsion：2 ± 0.2 kgf · cm





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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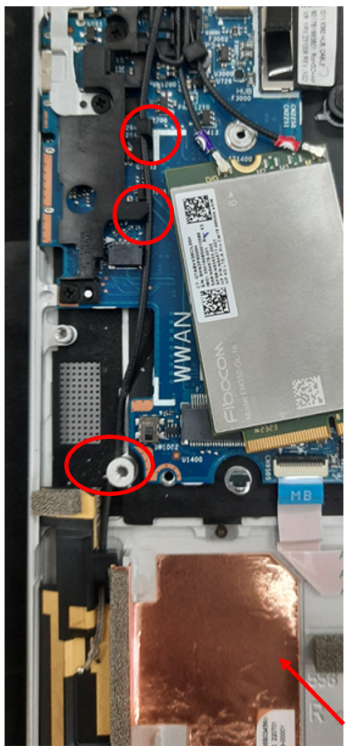
Standard operation guideline

Station: 8(1/1)

Operation name : Disassemble Antenna(7) Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble Antenna (7) from top case



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

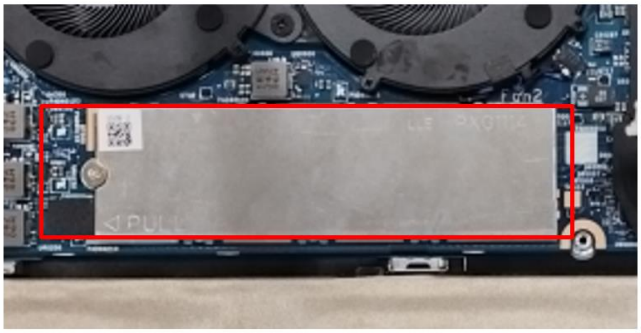
Standard operation guideline

Station: 9(1/1)

Operation name : Disassemble SSD Shielding can Ver. : 1.00 Date : 2024/3/1

Step :

1. Pull mylar，disassemble SSD shield can (PIC—)
2. Disassemble THM pad (PIC二)



PIC—



PIC二

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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Standard operation guideline

Station: 10(1/1)

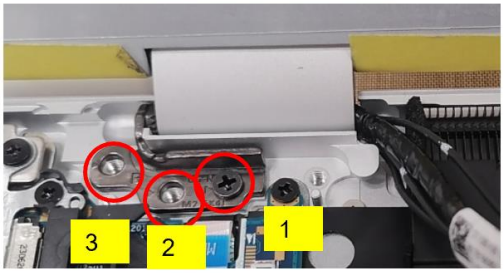
Operation name : disassemble Hinge up Ver. : 1.00 Date : 2024/3/1

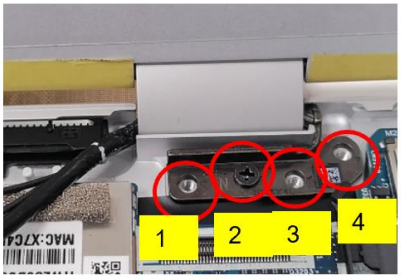


PIC—

Step :

1. Return Hinge up (PIC—)
   Unlock hinge up screw
   M2.5*4.0(6052B0101901))*7 (PIC二)
   ❖ Torsion： 3.5±0.2 kg/cm
2. Remove Hinge up (PIC三)





PIC二



PIC三

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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Standard operation guideline

Station: 11(1/1)

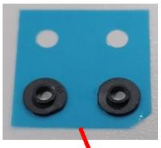
Operation name Disassemble SSD/WLAN/WWAN Module Ver: 1.00 Date : 2024/3/1

Step :

1. Disassemble WLAN/SSD screw M2.0*2.0(6052B0388301)*2 (PIC一)
2. Disassemble WWANM screw M2*3(6052B0537101)*1 (PIC二)
   - ❖ Torsion : 1.5±0.2kg/cm
3. For 4G WWAN card disassemble spacer(6051B1504201)(PIC二)

SSD







WWAN



WLAN





PIC一 PIC二

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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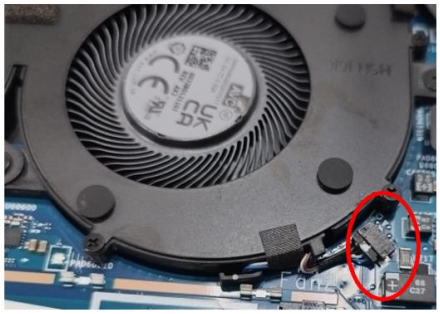
Standard operation guideline

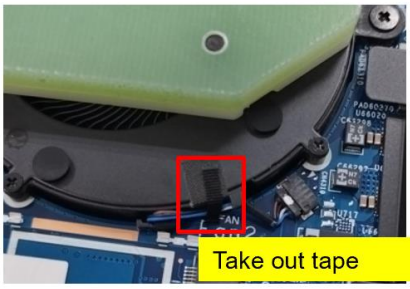
Station: 12(1/1)

Operation name :Disassemble fan CNTR Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble fan CNTR(PIC—)
2. Disassemble tape（6054B2708201）（PIC二）





PIC二



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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Standard operation guideline

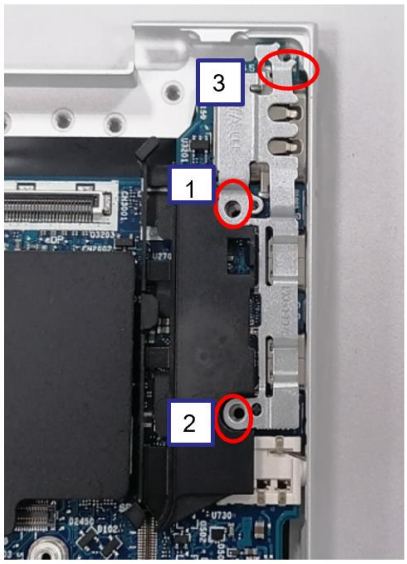
Station: 13(1/1)

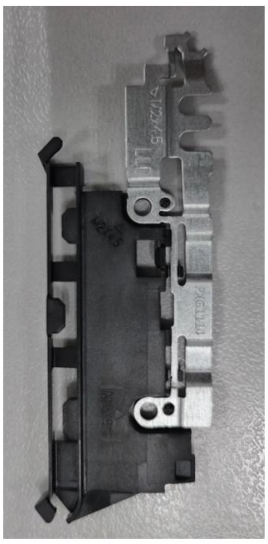
Operation name :Disassemble right I/O frame Ver. : 1.00 Date : 2024/3/1

6053B2219001	IO BRKT R Side
6051B1668101	IO Frame(R)

Step :

1. Disassemble screw M2*4.5(6052B0117602)*3(PIC—)
   - ❖ Torsion : 2.0±0.2 kg/cm
2. Disassemble IO/Frame and BRKT





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

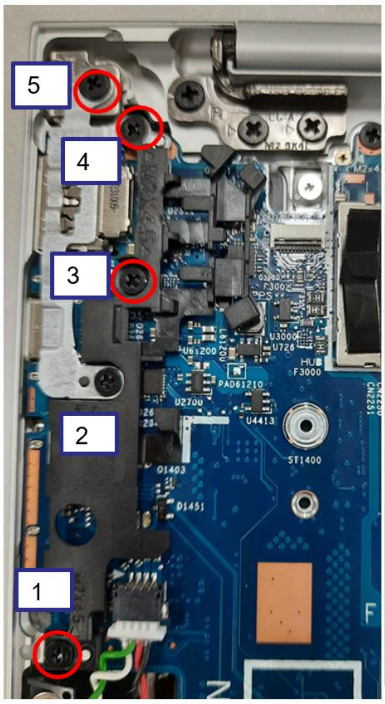
Station: 14(1/1)

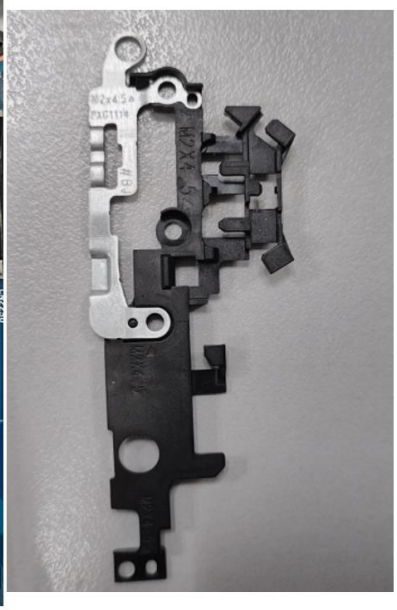
Operation name :Disassemble left I/O frame Ver. : 1.00 Date : 2024/3/1

6051B1668201	IO Frame(L)
6053B2218901	IO BRKT L Side

Step :

1. Disassemble screw M2*4.5(6052B0117602)*5(PIC—)
   - ❖ Torsion : 2.0±0.2 kg/cm
2. Disassemble IO/Frame and BRKT





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

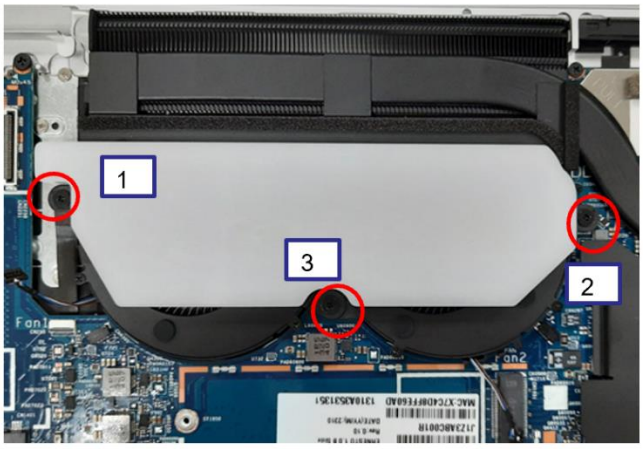
Standard operation guideline

Station: 15(1/1)

Operation name :Disassemble FAN Screw Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble Fan set screw*3 (PIC—)
   Torsion : 2.0±0.2 kg/cm



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / older / Tool / listen / Look / Hand / Static

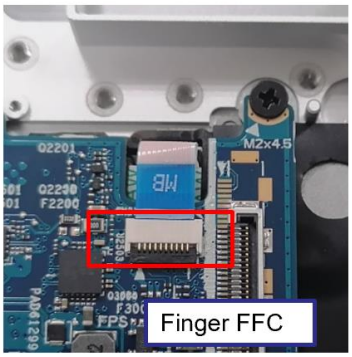
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Standard operation guideline

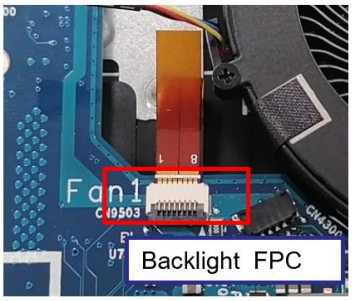
Station: 16(1/1)

Operation name :Disassemble FFC　　Ver. : 1.00　　Date : 2024/3/1

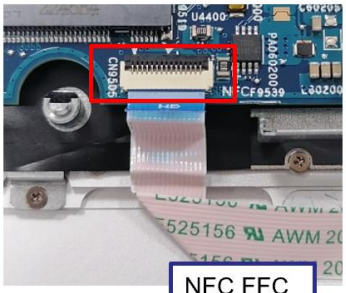


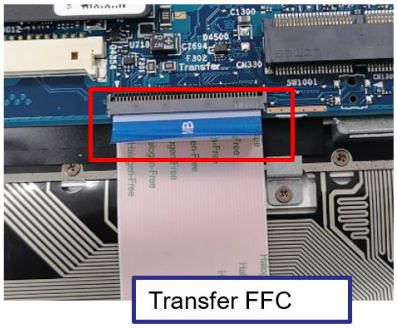
Step :

1. Disassemble Finger FFC、Backlight FFC
   NFC FFC、Transfer FFC于MB CONN
   (PIC—)









PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark							
		Safe	quality	Older	Tool	listen	Look	Hand	Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

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Standard operation guideline

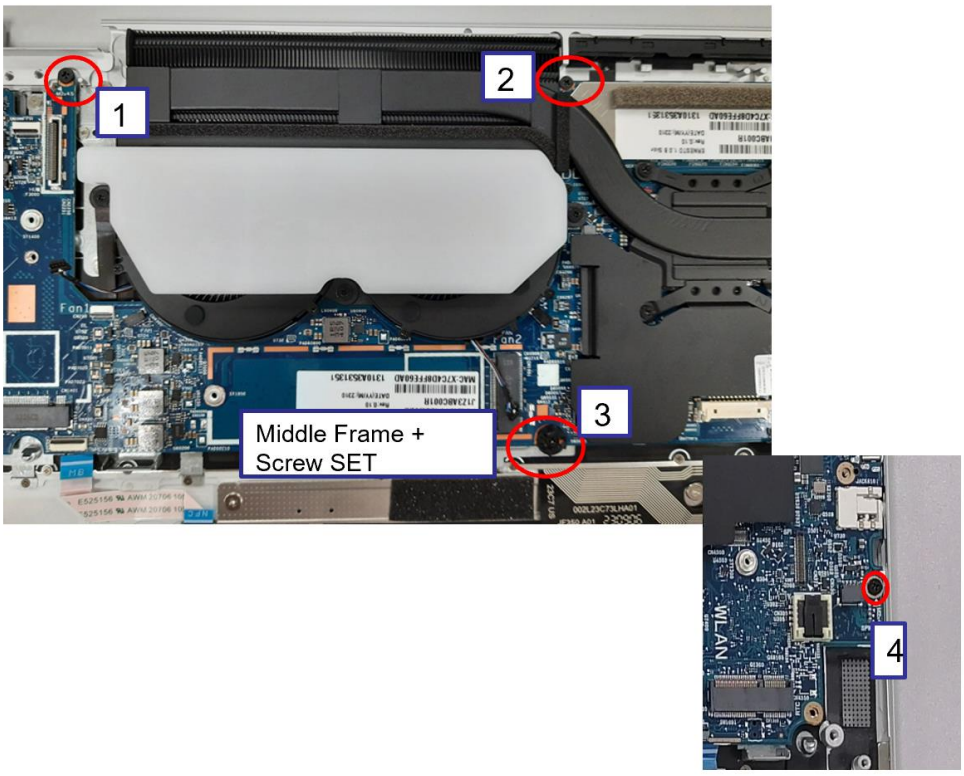
Station: 17(1/1)

Operation name :Disassemble M/B screw Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble screw M2*4.5(6052B0117602)*3
2. Disassemble sc Middle hook+screw

Torsion : 2.0±0.2 kg/cm



Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

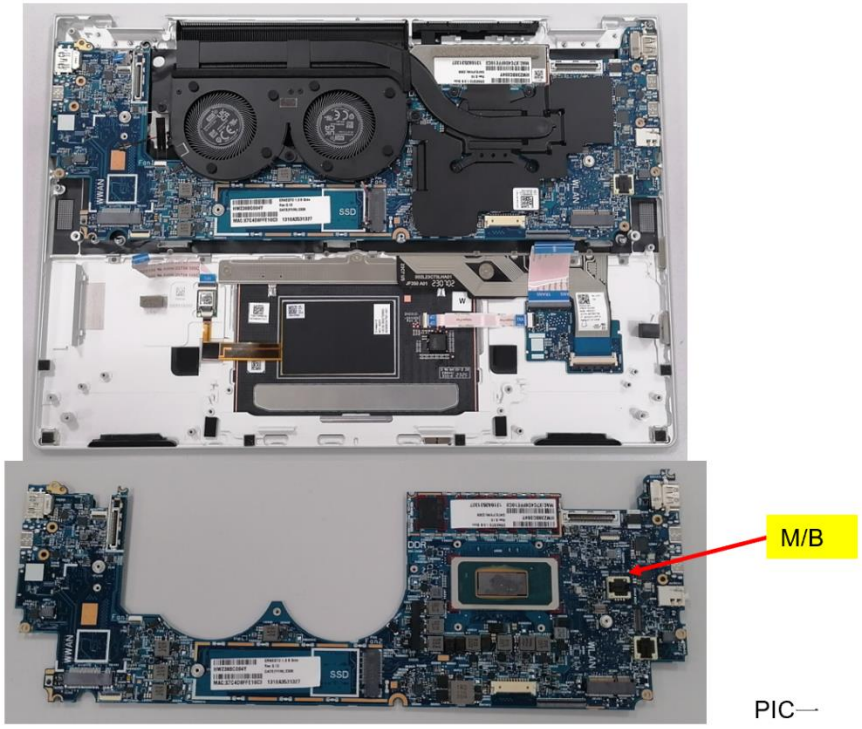
Standard operation guideline

Station: 18(1/1)

Operation name : Disassemble M/B Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble M/B from top case (PIC—)



PIC—

Notice：If have exception，please immediately notify offline handing

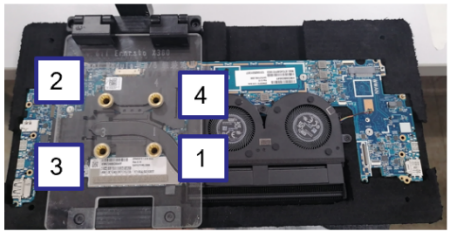
Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 19(1/1)

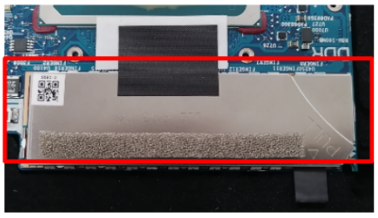
Operation name : Disassemble thermal module/DDR shield Ver : 1.00 Date : 2024/3/1



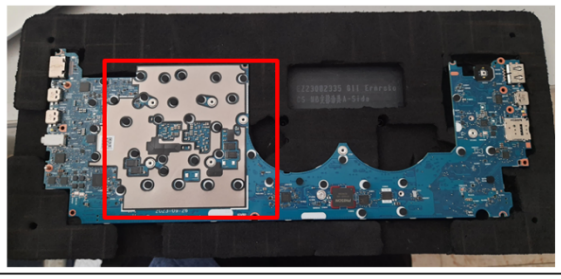
PIC一



PIC二



PIC三



PIC四

Step :

1. Disassemble thermal SET screw*4(PIC一)
   Torsion : 2.0±0.2 kg/cm
2. Disassemble Shielding can gasket (PIC二)
3. Pull mylar · Disassemble Shielding can gasket (PIC三)
4. Disassemble (6054B2949001)(PIC三)

6043B0406211	thermal module_X360 (CCI+AVC)
6043B0406201	thermal module_X360 (Delta)

Notice : If have exception · please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO : 3QBMDAP001-F003 version : 4 level : normal : Save date : New version Scrap style : Tear up

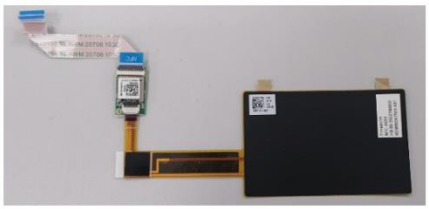
Standard operation guideline

Station: 20(1/1)

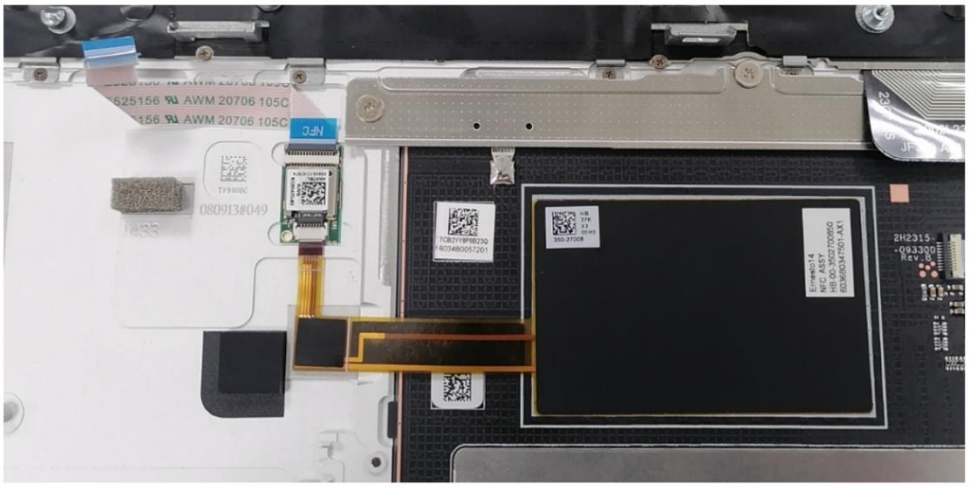
Operation name :Disassemble NFC Ver.: 1.00 Date : 2024/3/1

Step :

1. Disassemble NFC module from top case (PIC一)
2. Disassemble NFC Module(PIC二)



PI二



PIC一

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

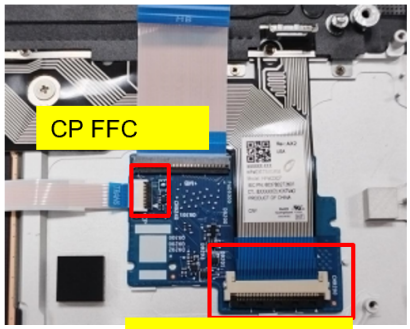
Standard operation guideline

Station: 21(1/1)

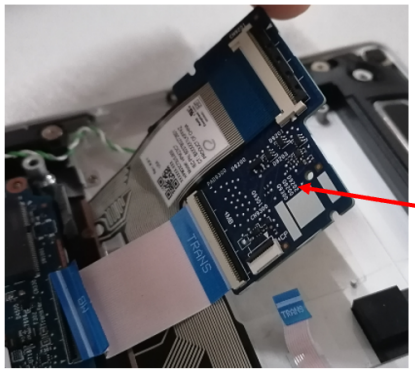
Operation name : Disassemble Transfer board Ver. : 1.00 Date : 2024/3/1

Step :

1. Take out Click Pad FFC 、Transfer FFC，(PIC一))
2. Disassemble Transfer board于top(PIC二)



PIC一



PIC二

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

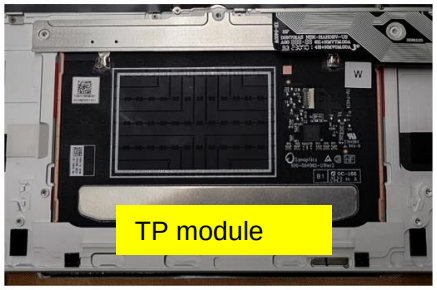
NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

Station: 22(1/1)

Operation name : Disassemble Click Pad Ver. : 1.00 Date : 2024/3/1

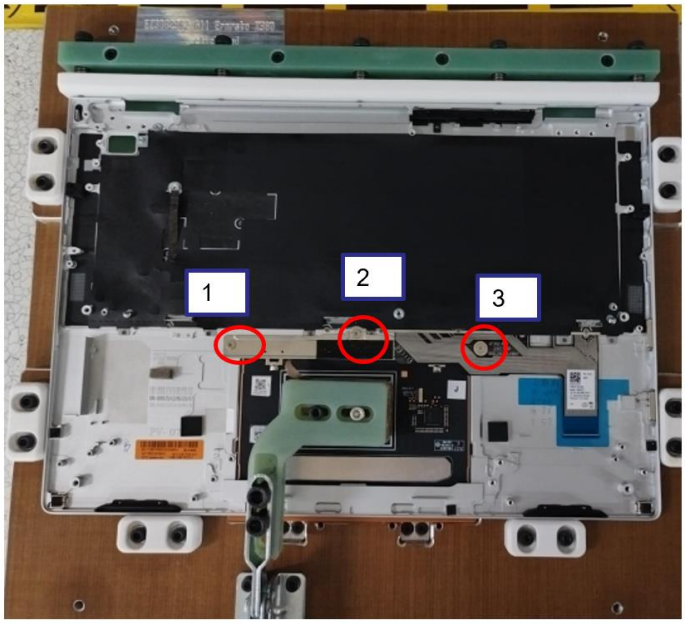


Step :

1. Disassemble Click pad screw M2*2 (6052B0156201)

   Torsion : 1.8 ± 0.2Kgf · cm

2. Remove TP Module (6034B0057101/6034B0057201)



Notice : If have exception , please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#1)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO : 3QBMDAP001-F003 version : 4 level : normal : Save date : New version Scrap style : Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

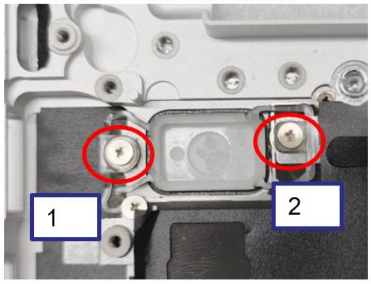
Station: 23(1/1)

Operation name : Disassemble POWER button/FP Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble screw(6052B0569601)* 2 (PIC一/二)
   - ❖ Torsion ：0.5~0.7Kgf · cm
2. Disassemble POWER KEY/FP

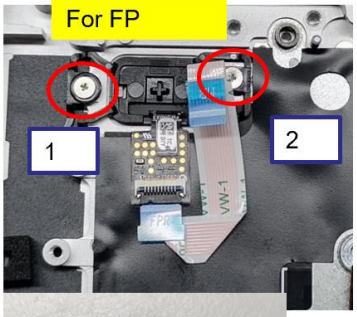
For power button





PIC一

For FP





PIC二

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

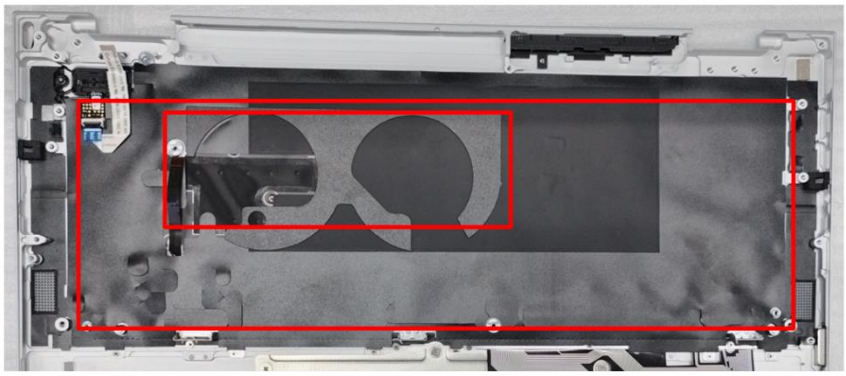
Standard operation guideline

Station: 24(1/1)

Operation name : Disassemble Mylar Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble Mylar(6054B3028601)/ Mylar(6054B2951801)



PIC一

Notice：If have exception，please immediately notify offline handing

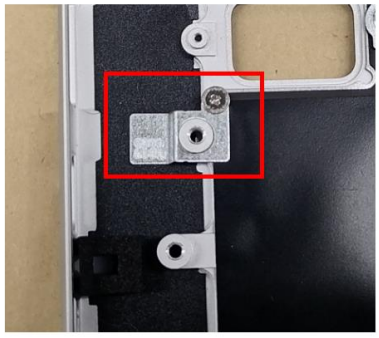
Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 25(1/1)

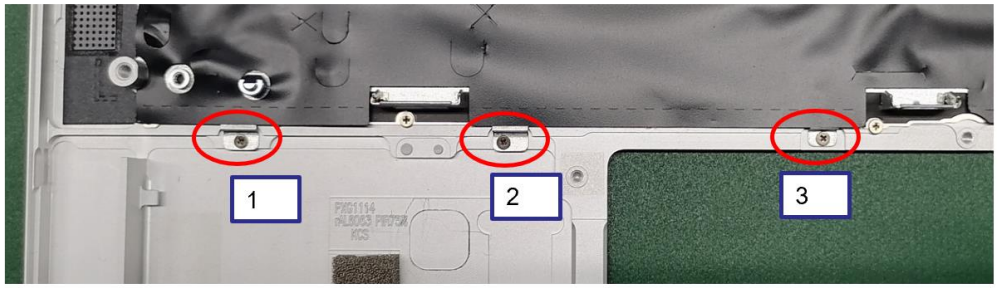
Operation name : Disassemble BRKT screw Ver. : 1.00 Date : 2024/3/1



Step :

1. Disassemble SUP BRKT screw (PIC—)
   - ❖ Torsion :0.4~0.6kgf.cm
   - ❖ screw : 6052B0714701 quantity : 6
2. Disassemble Hall Sensor BRKT(6053B2217501) (PIC二)
   - ❖ screw : 6052B0569601 quantity : 1
   - ❖ Torsion :0.4~0.6kgf.cm

PIC二





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

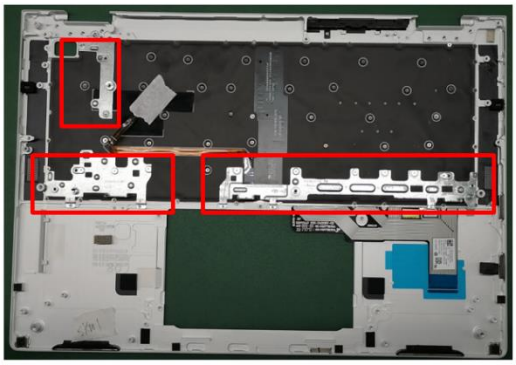
Standard operation guideline

Station: 26(1/1)

Operation name : Disassemble BRKT Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble BRKT(PIC—)
   - Torsion :0.4~0.6kgf.cm
   - screw : 6052B0569601 quantity : 13



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

Station: 27(1/1)

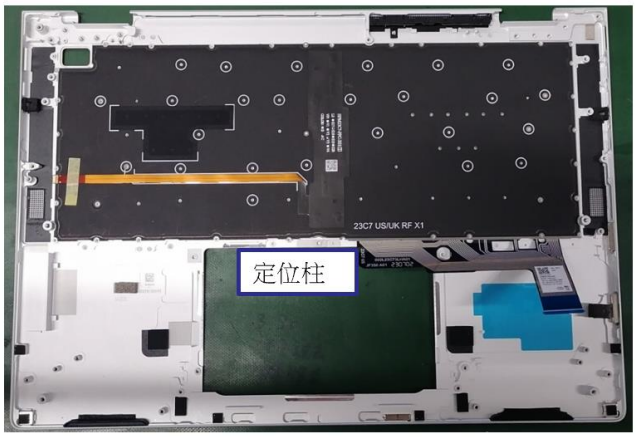
Operation name : Disassemble Keyboard Ver. : 1.00 Date : 2024/3/1





Step :

1. Disassemble KB screw(PIC—)
   - ❖ Torsion :0.4~0.6kgf.cm
   - ❖ screw : 6052B0714701 quantity : 53



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 28(1/1)

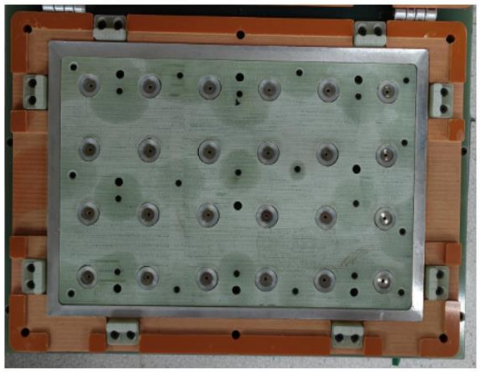
Operation name : Disassemble Hinge up Ver. : 1.0 Date : 2024/3/1



PIC一

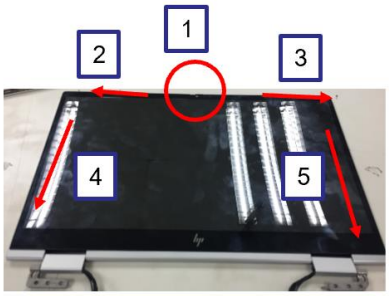
Step :

1. Put Hinge up into the heater tool (PIC一/二)
   - Temp:85±3°
   - Time : 10 Min
2. Open the hinge up use open bar(PIC三)





PIC二



Disassemble hinge up from shutter location，Reference 1/2/3/5

PIC三

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Hinge up heating fixture Open bar	1 1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 29(1/1)

Operation name :Disassemble Hinge holder Ver. : 1.00 Date : 2024/3/1





Step :

1. Disassemble Hinge holder

6051B1662801	Hinge cap holder L
6051B1663101	Hinge cap holder R

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

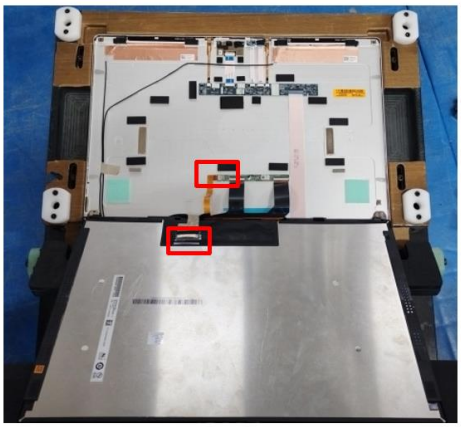
Standard operation guideline

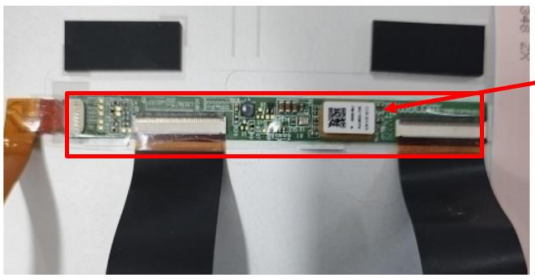
Station: 30(1/1)

Operation name : Disassemble B SET Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble EDP CNTR、Touch FPC CNTR(PIC—)





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

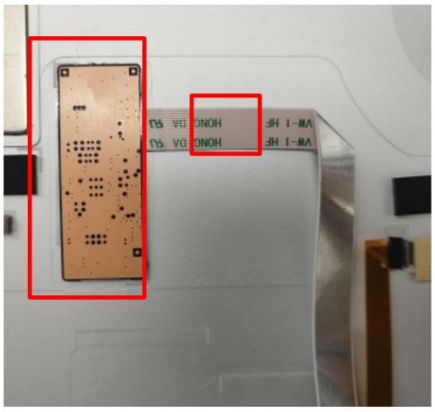
Station: 31(1/1)

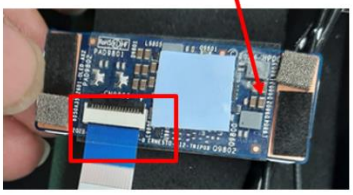
Operation name : Disassemble PMIC/B Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble PMIC/B(PIC—)

For OLED Panel





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

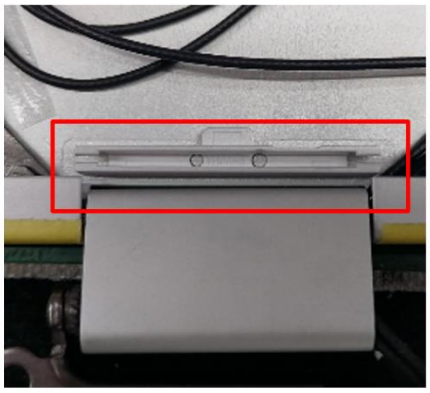
NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

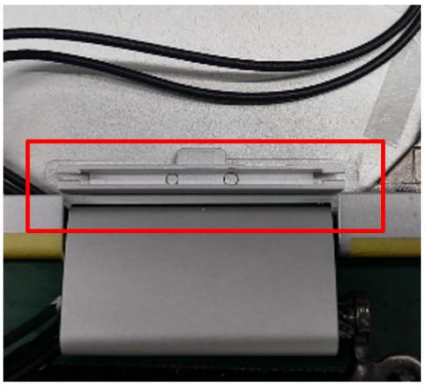
HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

Station: 32(1/1)

Operation name : Disassemble cable holder Ver. : 1.00 Date : 2024/3/1





Step :

1. Disassemble cable holder（6051B1662901）*2

PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

HP Inc. instructions for this template are available at EL-MF877-01

Standard operation guideline

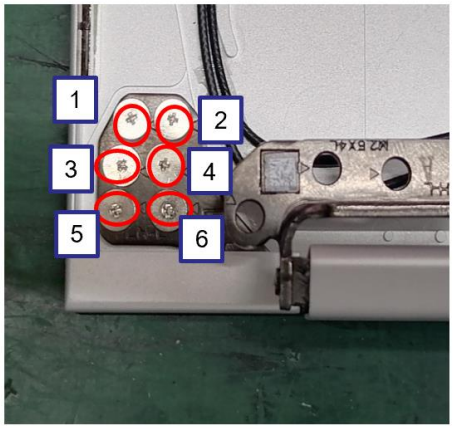
Station: 33(1/1)

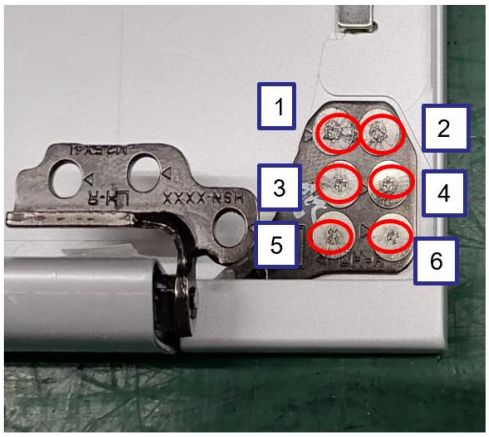
Operation name : Disassemble hinge screw Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble HingescrewM1.4*1.4 (6052B0729101)*12 (图二)

❖ Torsion : 1.4±0.1 kgf • cm





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

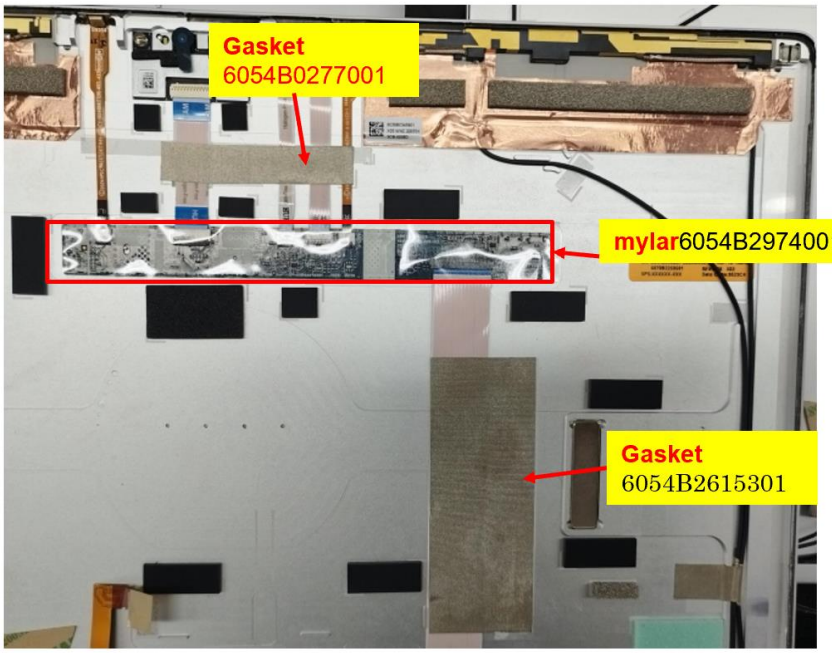
Standard operation guideline

Station: 34(1/1)

Operation name : Disassemble Mylar、gasket Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble
Mylar(6054B2974001)于HUB/B
Gasket (6054B2615301)*1贴于A-cover
Gasket (6054B0277001)*1贴于A-cover



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

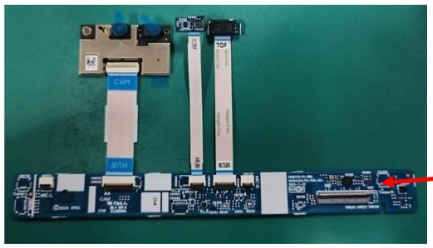
Standard operation guideline

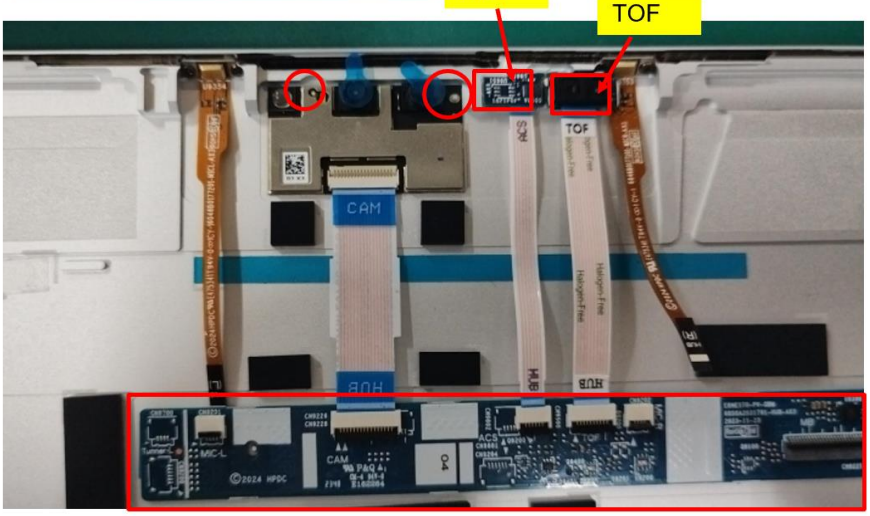
Station: 35(1/1)

Operation name :Disassemble camera/ACS/TOP /HUB Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble camera/ACS/TOF/HUB (PIC—)





PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

Station: 36(1/1)

Operation name : Disassemble WWAN Antenna Ver. : 1.00 Date : 2024/3/1

Step :

1. Disassemble Antenna(PIC—)



PIC—

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
		Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up

Standard operation guideline

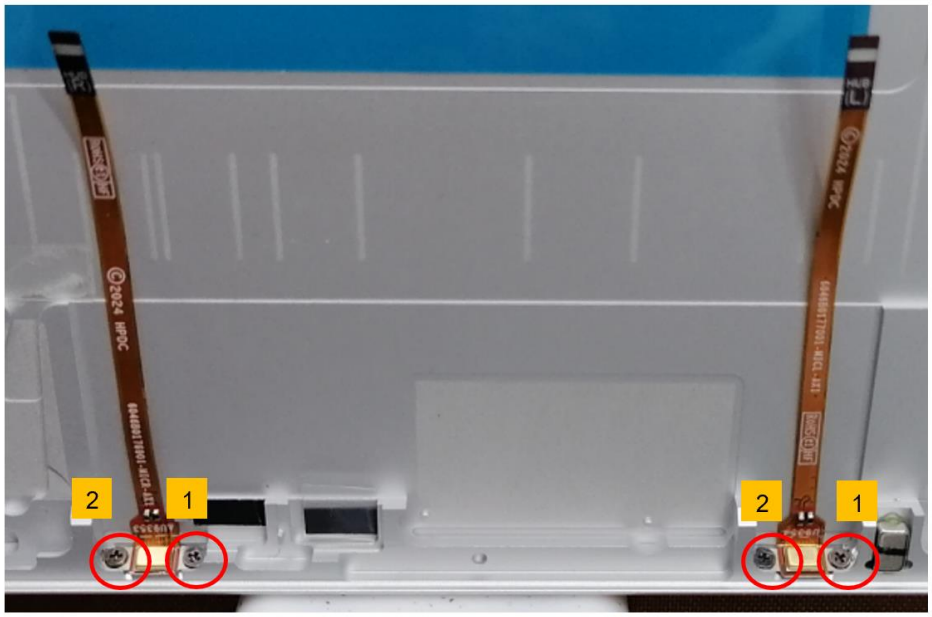
Station: 37(1/1)

Operation name : Disassemble MIC Ver. : 1.00 Date : 2024/3/1

6046B0177001	MIC L FPC 圓裕
6046B0176901	MIC R FPC 圓裕
6046B0177401	MIC L FPC 寶軒
6046B0177301	MIC R FPC 寶軒
6046B0177201	MIC L FPC 傳藝
6046B0177101	MIC R FPC 傳藝

Step :

1. Disassemble MIC (PIC一)
❖Torsion ：0.6~0.8 Kgf · cm
❖screw： M1.2*1.5(6052B0138801)*4



图一

Notice：If have exception，please immediately notify offline handing

Tool list(Tool rule)	Qua	Mark
Electric screw drive (#0)	1	Safe / quality / Older / Tool / listen / Look / Hand / Static

NO：3QBMDAP001-F003 version：4 level：normal：Save date：New version Scrap style：Tear up